



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: DSNO-11CVSI654

Date:
March 12, 2026

**Qualification of ATP7 as an additional assembly site for
AT9919K7-GVAO, HV9918K7-G, HV9919BK7-G, AT9919K7-G and
HV9967BK7-G catalog part numbers (CPN) available in 8L WDFN
(3x3x0.8mm) package.**



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of ATP7 as an additional assembly site for AT9919K7-GVAO, HV9918K7-G, HV9919BK7-G, AT9919K7-G and HV9967BK7-G catalog part numbers (CPN) available in 8L WDFN (3x3x0.8mm) package.
CN	E000279061
QUAL ID	R2501524 Rev. A
Bonding No.	BD-003145 Rev.02
MP CODE	VAGA2YUQXVA1
Part No.	AT9919K7-GVAO
CCB No.	7630
<u>Lead Frame</u>	
Paddle size	106 x 75
Material	C194
Surface	Ring Ag
Process	Etch
Lead lock	Yes (Half Etch)
Part number	101431257
Plating composition	Matte Sn
<u>Bond Wire</u>	
Wire	Au
<u>Die Attach Material</u>	
Epoxy	AP4300
<u>Mold Compound</u>	
Mold compound	G631BQF
<u>Package</u>	
Type	8L WDFN
Package size	3 x 3 x 0.8mm



MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
ATP7263000012.000	TC08925010580.400	2543K3H
ATP7263000013.000	TC08925010580.400	2543K42
ATP7263000014.000	TC08925010580.400	2543K4B

Result

☒ Pass ☐ Fail ☐ _____

8L WDFN (3x3x0.8mm) assembled by ATP7 pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 3)	Electrical Test: +25°C System: TMT_LV_NT	JESD22- A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max			693		
	System: Vitronics Soltec MR1243					
	Electrical Test: +25°C System: TMT_LV_NT		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +150°C, 1000 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_LV_NT		231 (0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>4.00 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_LV_NT		231(0)	0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.0 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_LV_NT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: TPS Bake Oven Electrical Test: +25°C System: TMT_LV_NT	JESD22-A103	45(0)	45 0/45	Pass	45 units
Solderability Temp 215°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000 Solder Dipping: Solder Temp 215°C Solder material: SnPb Sn63, Pb37 System: ERS A RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	22 0/22	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000 Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERS A RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	22 0/22	Pass	
Wire sweep	Wire sweep Inspection 15 Wires / lot	-	45(0) Wires	0/45	Pass	
Physical Dimensions	Physical Dimension, 10 units / 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>4.00 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>10.00 grams)	CDF-AEC-Q100-001	30(0) Bonds	0/30	Pass	